

FIG. 1a

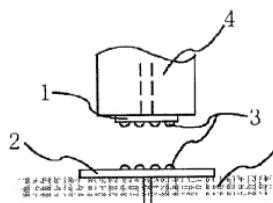


FIG. 1b

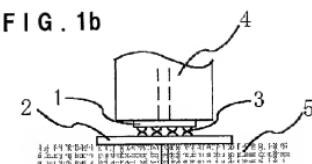


FIG. 1c

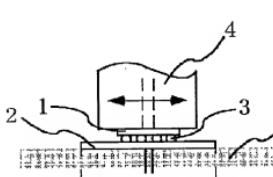
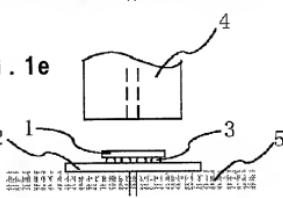
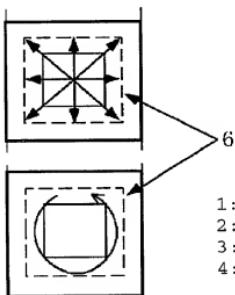


FIG. 1e



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FIG. 1d



- 1: semiconductor element
- 2: wiring board
- 3: solder bump
- 4: ultrasonic bonding head

FIG. 2

